VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION:

Please amend the specification as follows:

Page 39, Paragraph 9, continuing on Page 40

FIGS. **20(a)** through **[20(d)]** **20(c)** are cross-sectional views of process steps of the fabricating method for a semiconductor device of the eighth embodiment of the present invention.

Page 85, Paragraph 2

A semiconductor device and a fabricating method therefor of the eighth embodiment will be described with references to FIGS. **19(a)** to **19(c)** and **20(a)** to **[20(d)]** **20(c)**.